



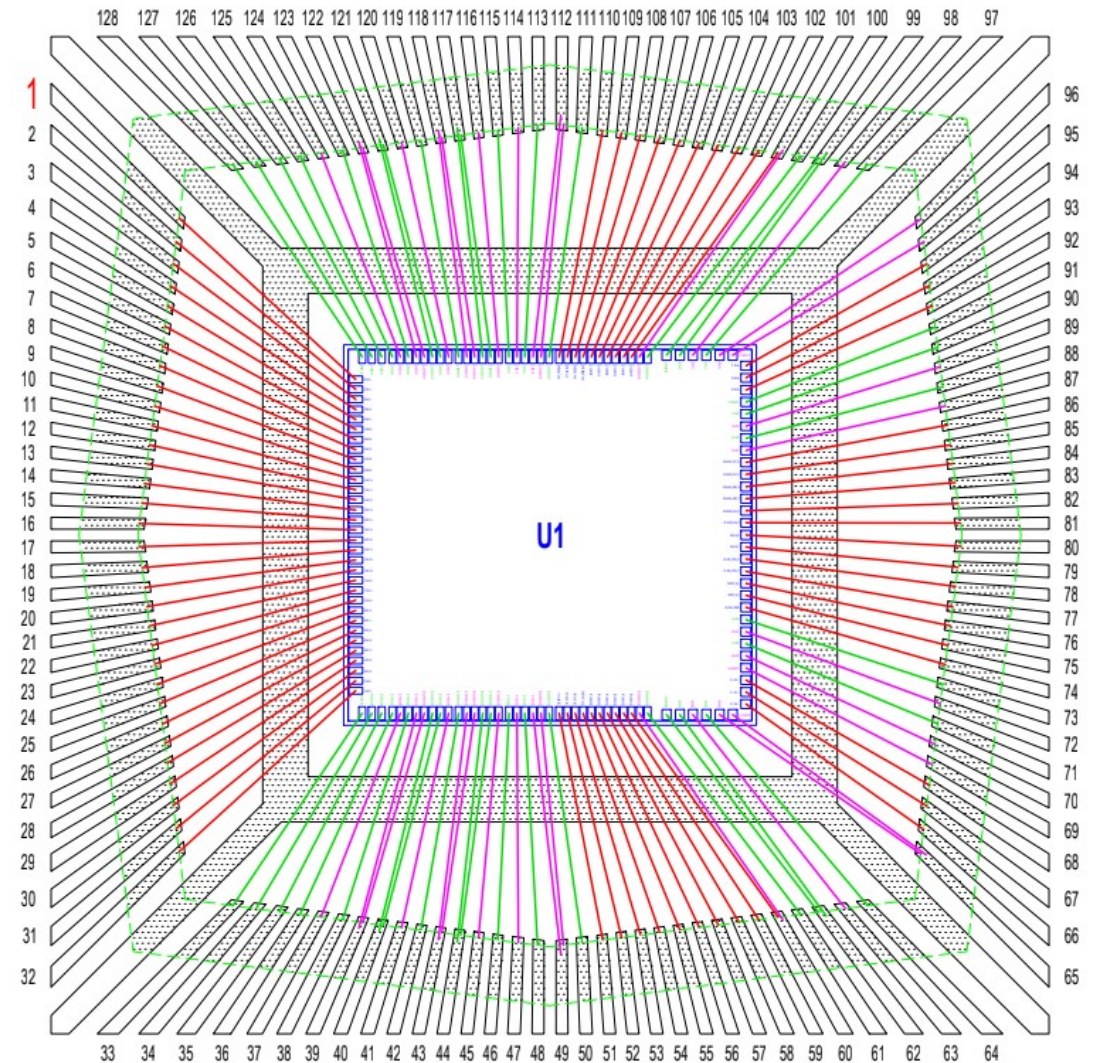
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## Readout status and plan

ECAL working group meeting, 24.01.24

## Current readout status – **FLAXE ASIC**

- Technical details about packaging fixed (bonding scheme, marking)
  - We should get final confirmation and shipping date around 10<sup>th</sup> of February
- The expected shipping date of ~1000 packaged ASICs is around ~April 2024



- With the bonding scheme fixed, I just (this week) started the design of:
  - Single FLAXE ASIC test board – required for ASIC verification and characterization
    - Schematic almost done, PCB not started yet
    - This board have to be ready till the end of Q1 2024 (before ASICs arriving)
  - FEB design
    - Lot of issues still to be resolved (like connector from FEB to patch panel)
    - At least the “front-end” (fanout connectors, ASICs placement and decoupling) should be done asap (hopefully before Valencia meeting) since it is needed for the fanout and HV flex design by Yan
    - Foreseen to be ready till the end of Q2 2024

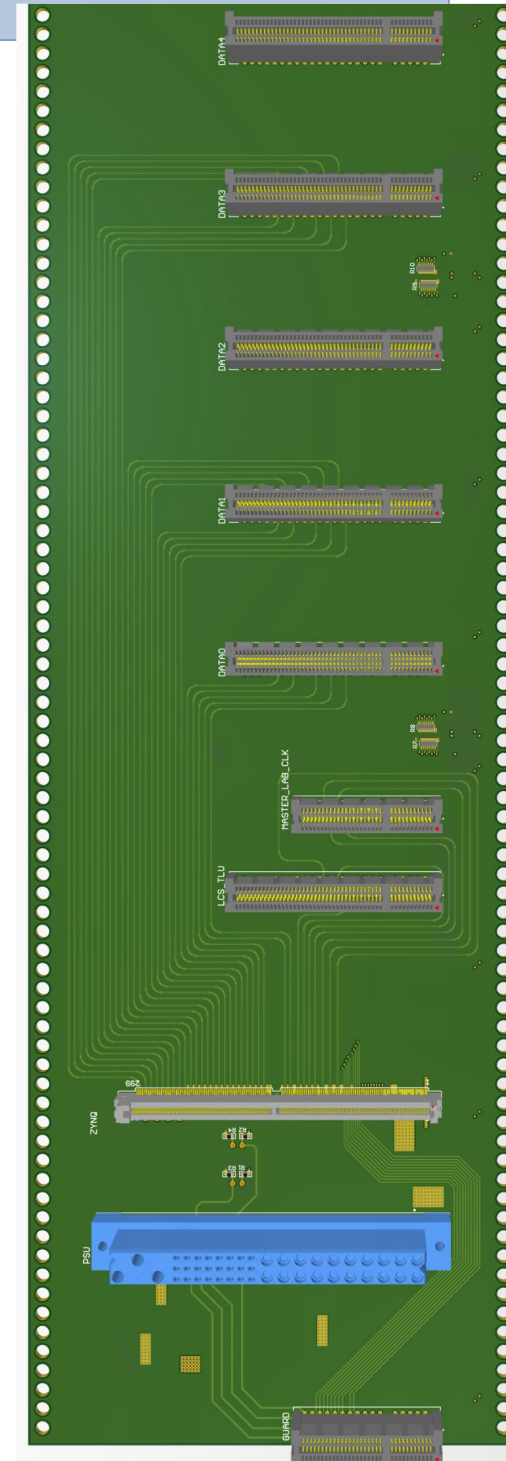
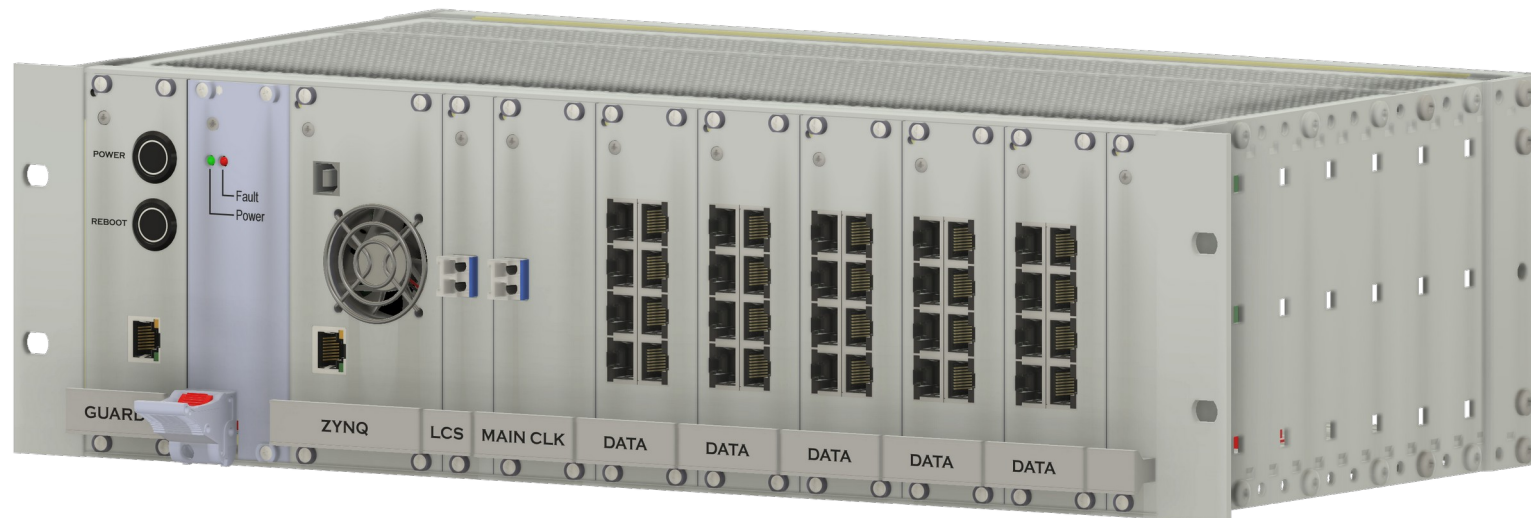


## Current readout status – **DAQ hardware**

DAQ hardware (PCBs and mechanics) in progress:

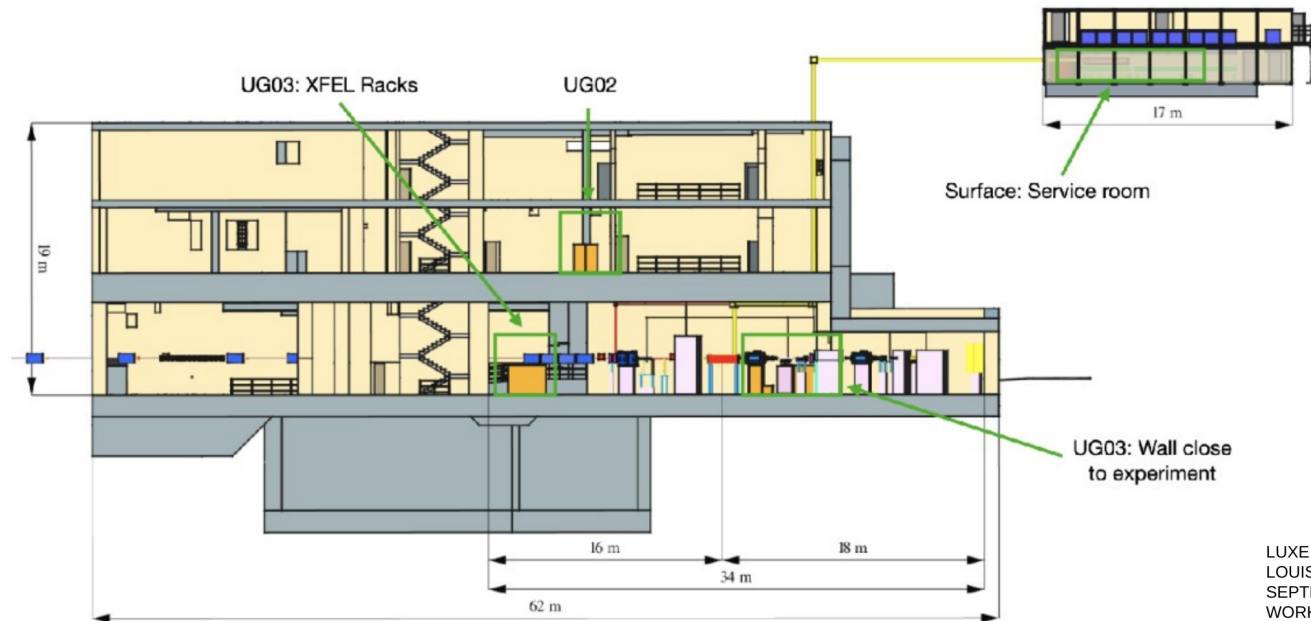
- Mechanic is fixed (19" Eurorack from nVent Schroff)
  - 3D model with all cards and connectors prepared and verified
  - One rack already bought for tests
- PCBs:
  - Backplane almost ready (schematic and PCB)
  - Cards in progress (schematics in progress, PCB – only mechanics-related components placed)

**Target: complete DAQ (one rack) and FEB (how many?) for testbeam in Q3 2024**



## Current readout status – **data and clock transmission medium**

We have tested the cables (and fibers) to communicate DAQ rack with the FEBs in the cavern (~60m)



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• **Position foreseen for backend electronics:**

- In UG03 (not accessible during data-taking).
- In UG02 (potentially accessible at every time but for short stay and space limited).
- In surface building (further away), space to be understood.

Area	Length
UG03: Side north wall	7 m
UG03: EuXFEL rack	16 m
UG02	26 m
Surface: service room	≈ 50 m

### Targets:

- Find a medium to transmit the system clock and acquisition control signal from DAQ to the cavern with long-term phase drift  $< 1\text{ns}$
- Check if Cat6/6a RJ45 cables (widely available and cheap) can be used to send data from the cavern to the DAQ

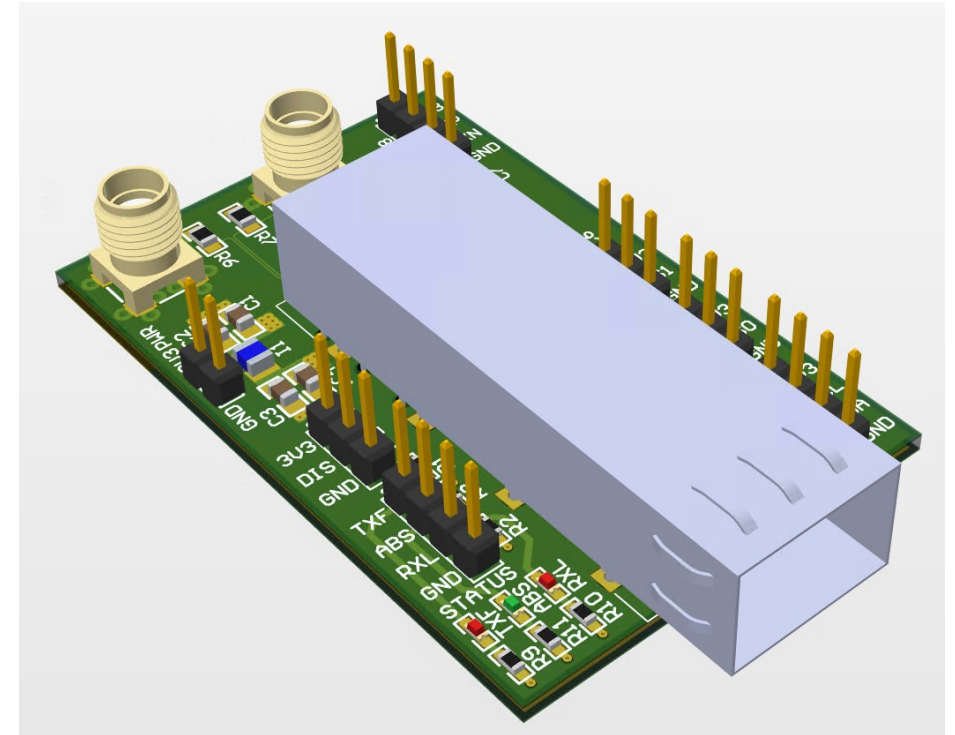
## Current readout status – **data and clock transmission medium**

### Test setup:

- Signal generator providing 20MHz square wave
- Custom “SFP breadboard” PCB, commercial 1Gbps SFP modules (GBC PHOTONICS SF-MM85055D-GP, FOUNDRY TXN3111100000001), 50m long multi-mode fiber (OM2 Qoltec 54030)
- 50m long, low-loss 50 $\Omega$  coaxial cable Siva Cavi RF240LTA (1.4 EUR / m)
- 50m long Cat6a RJ45 cable Logilink CQ3143S
- High speed scope measuring the signal delay and jitter
- Climatic chamber

### Test program

- Delay and jitter measurements for temperature in range from -20 to +50 °C
- *Delay and jitter measurements for varying humidity (not done yet)*

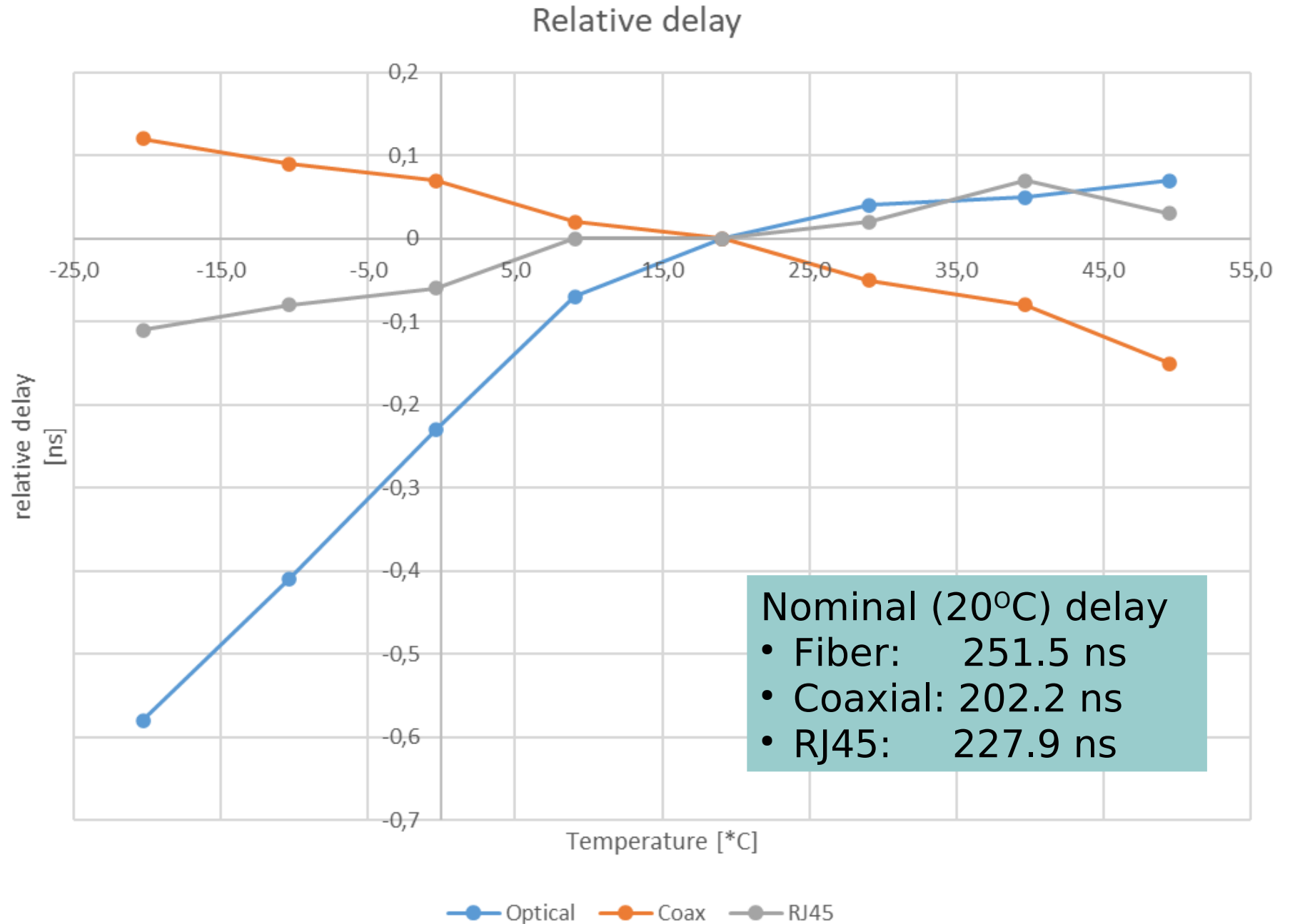


## Delay drift

All three medium have drift <1ns

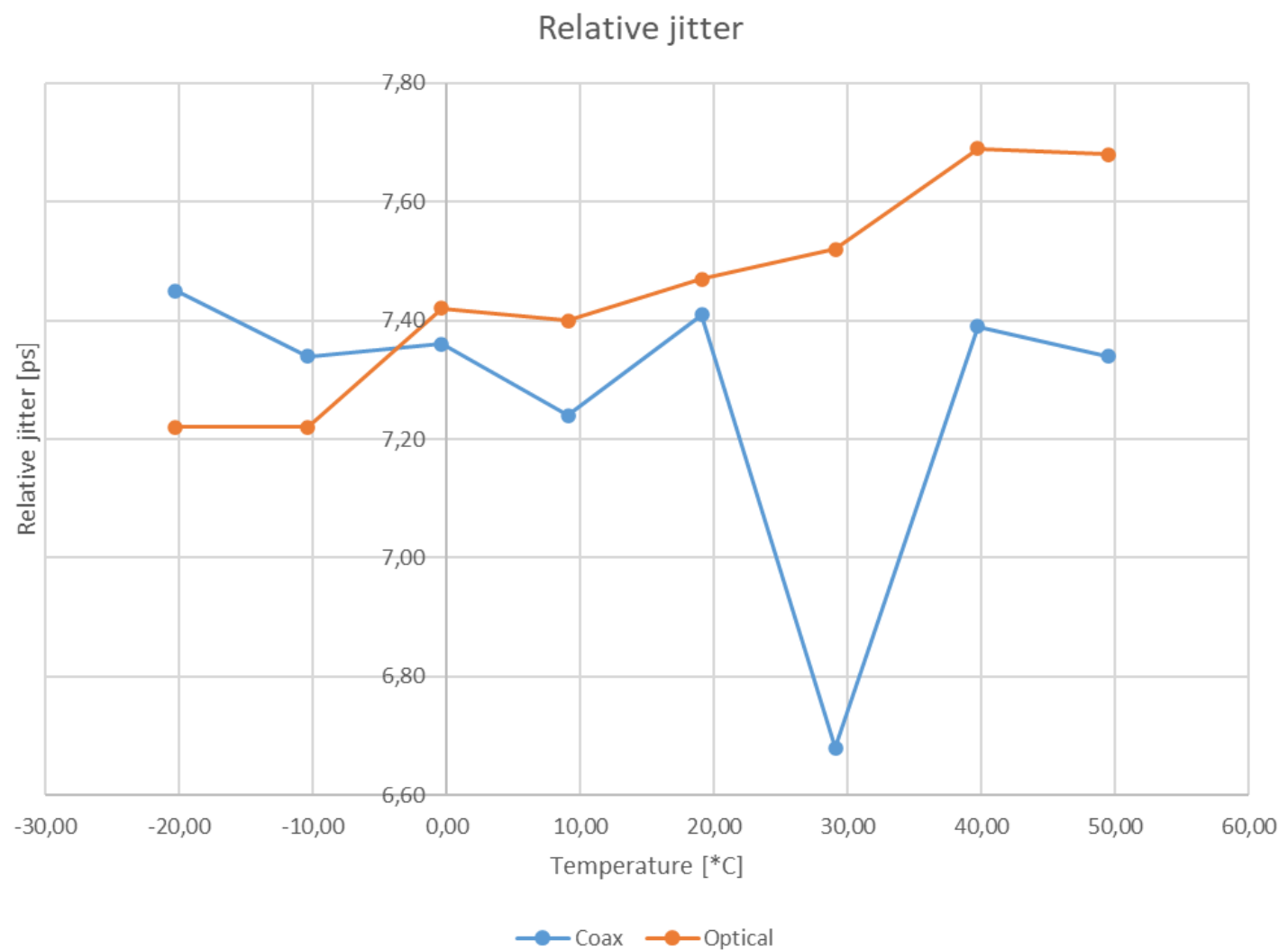
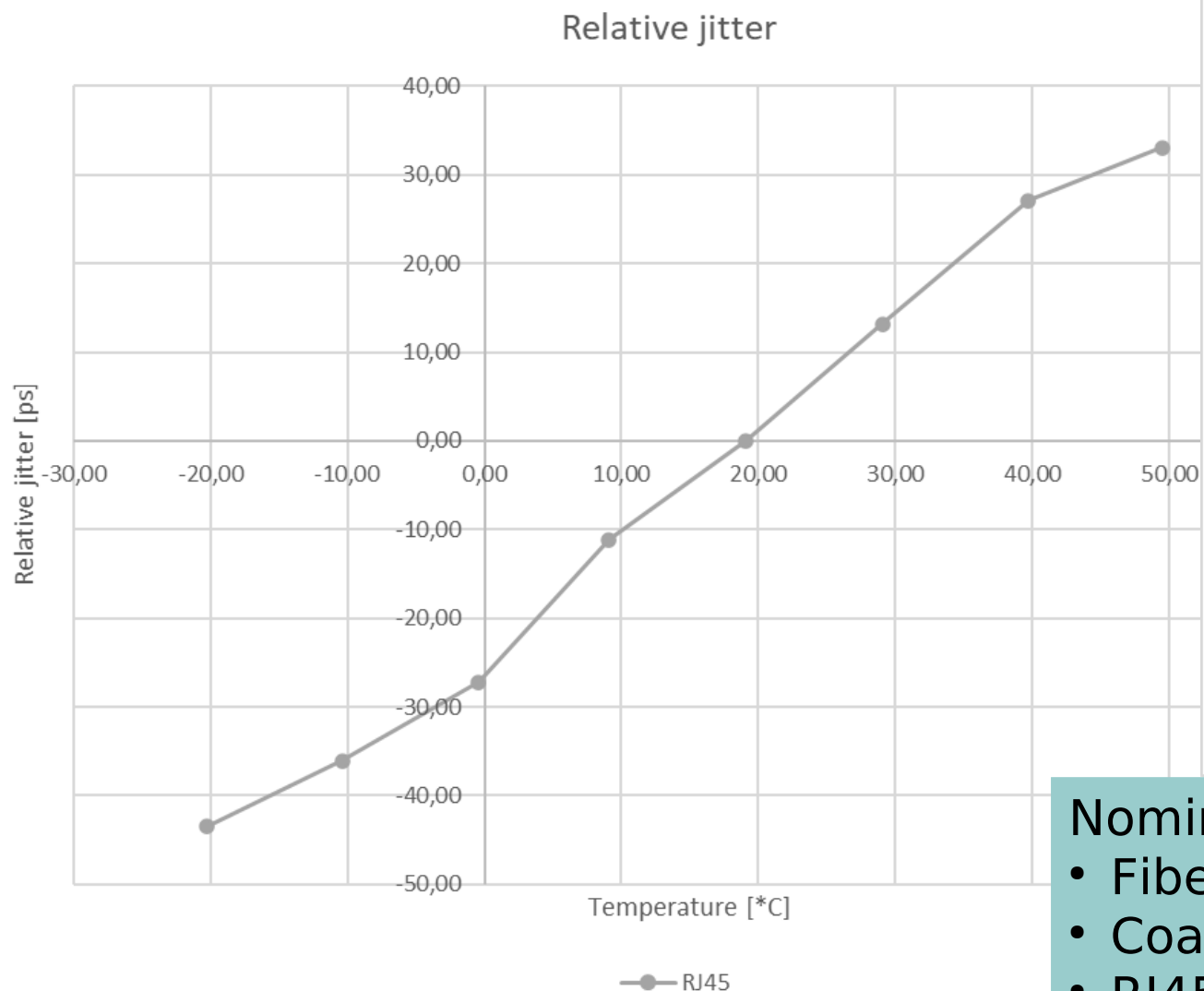
Fiber is surprisingly the worst one ranging from -0.6ns to +0.1ns!!

Coaxial cable seems the best choice, with drift < ±150ps



## Relative jitter

RJ45 – too large for clock, ok for data



Nominal (20°C) jitter

- Fiber: 7.4 ps
- Coaxial: 7.4 ps
- RJ45: 161 ps

Fiber, coaxial – ok!



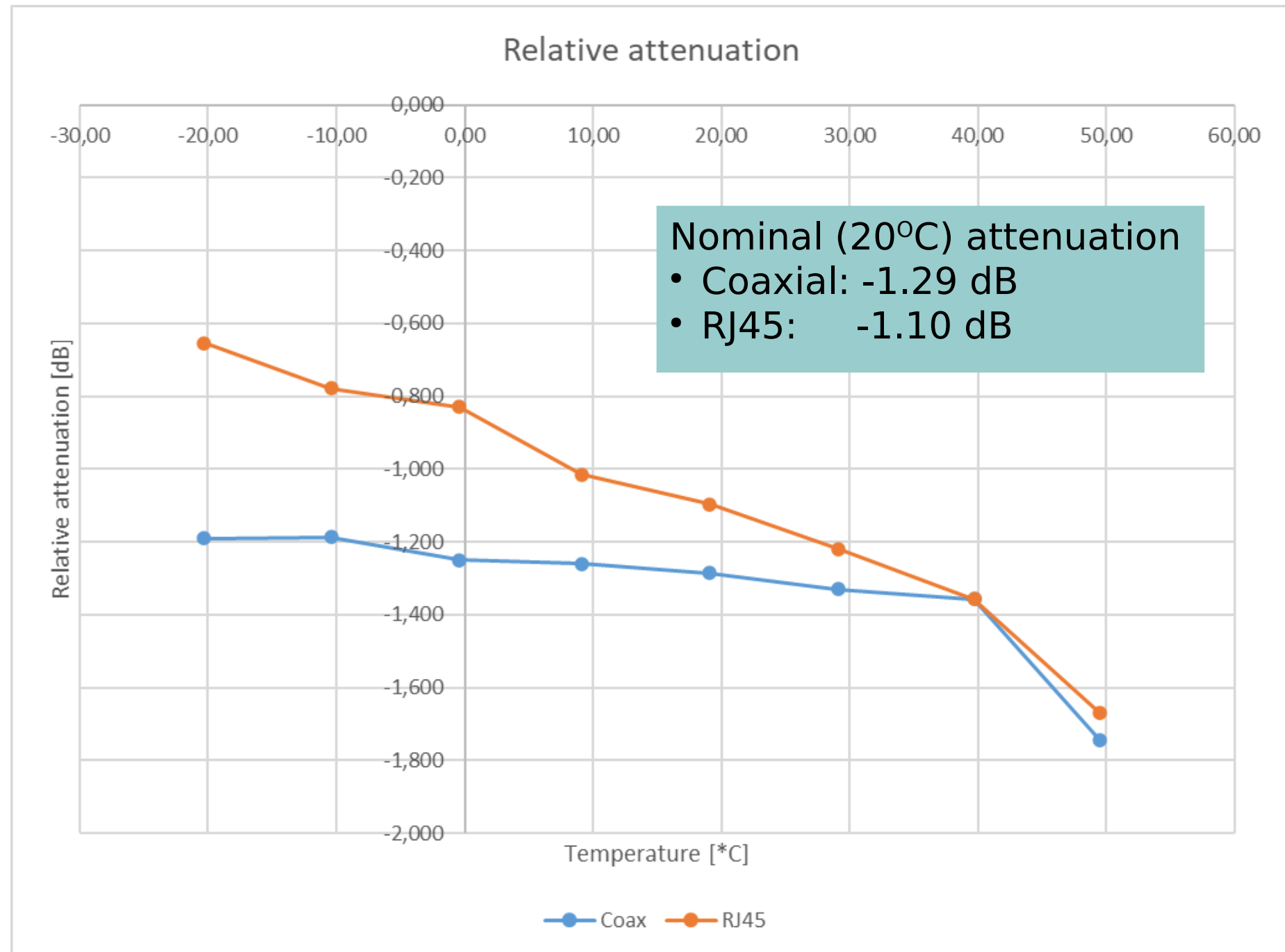
## Attenuation

Both coaxial and RJ45 attenuation well suited for clock and data transmission:

Worst case is -1.8dB (80% of original amplitude) after 50m.

We can expect less than -3.5dB (67% of the original amplitude) after 100m

*No attenuation data for fiber since SFP receiver recreates the electrical signal*



## Current readout status – summary and schedule

	1	2	3	4	5	6	7	8	9	10
Task	January	February	March	April	May	June	July	August	September	October
1 FLAXE test PCB design										
2 FLAXE test PCB fabrication										
3 Test setup development (miniDAQ)										
4 FLAXE verification										
5 FLAXE characterization										
6 FEB design										
7 FEB fabrication										
8 DAQ PCB design										
9 DAQ PCB fabrication										
10 DAQ hardware tests										
11 DAQ firmware development										
12 Possible DAQ PCB redesign										
13 System tests and debug (FEB + DAQ)										
14 Testbeam										

### Comments:

- Currently I am working on all of this completely alone
  - Most likely a (very good) master student should join within ~month
  - Together with Dawid they can take all the “verification / characterization / tests” tasks leaving me with all the design
  - Please understand that I am not able to take care of the TB data integrity in parallel
- There is no place in schedule for EUDAQ software! There will be DAQ software of course, but not integrated with EUDAQ without help from others!

## Current readout status – **summary and schedule**

- One of the the main showstoppers – clock and other signals distribution – resolved
- No info about ASICs fabrication progress (no bad info is a good info), ASICs expected ~April
- Hardware design in progress, no delay or showstoppers so far
- Firmware not yet started, but (at least for the first testbeam) it is not a huge task
- No time to prepare EUDAQ integrated software. Can someone with:
  - C/C++ experience,
  - EUDAQ knowledge (or willing to learn)help to develop it? (not now, rather end of Q2 2024)
- We are searching for post-doc (software or hardware oriented would be best)
- **Our goal is a testbeam at the end of Q3 2024 with at least one FEB (layer)**
- We need dose and neutron equivalent flux estimation in the space above the ECAL to
  - start the patch panel PCB design!
  - complete the FEB design!